

Description

The present invention relates to a method of manufacturing a semiconductor device and, more particularly, to a method of manufacturing a reliable and highly integrated wiring.

Fig. 1 is a sectional view of two memory cells of a Dynamic Random Access Memory (DRAM). N-type diffusion regions 12 and 13 of storage capacitors and a n-type diffusion region 14 of a selection transistor are formed on a p-type semiconductor substrate 11. Capacitor electrodes 16 and 17 made of polysilicon are formed on insulating layers 15 overlying n-type diffusion regions 12 and 13. Word lines 19A and 19B made of polysilicon are formed on a part of semiconductor substrate 11 which is located between n-type diffusion region 12 and n-type diffusion region 14, and between n-type diffusion region 13 and n-type diffusion region 14, respectively. Word lines 19C and 19D of other memory cells are formed on capacitor electrodes 16 and 17, respectively, and insulating interlayer 23 is formed to cover the semiconductor structure. A contact hole 24 to the surface of n-type diffusion region 14 is formed in insulating interlayer 23, and a bit line 25 is formed to connect with n-type diffusion region 14 through contact hole 24.

Fig. 2 shows an equivalent circuit of memory cells having the structure shown in Fig. 1. Each memory cell consists of a capacitor C and a selection transistor Q, each diffusion region of selection transistor Q is connected in common with a bit line BL, and a gate electrode of selection transistor Q is connected to respective word lines WL.

In the manufacturing method, since contact hole 24 is formed through insulating interlayer 23, it is necessary to allow a dimension margin L between word lines 19A and 19B to prevent any short circuit between each word lines 19A and 19B and bit line 25. For example the dimension margin L needs about $1.0\ \mu$ for $1.0\ \mu$ design rule device; therefore, according to conventional manufacturing methods, it is difficult to improve the microminiaturization of the structure.

To solve this problem, in another conventional method, the microminiaturization of the memory cell is realized by the method as shown in Figs. 3(a) - 3(c). In this method, after n-type diffusion regions 32 and 33 are formed on a p-type semiconductor substrate 31, an insulation layer 34 and capacitor electrodes 35 and 36 are formed. A silicon dioxide layer, a polysilicon layer and a CVD silicon dioxide layer are formed on the semiconductor structure, successively, and are respectively formed into a gate oxide layer 37; word lines 38A, 38B, 38C and 38D; and CVD silicon dioxide layers 39A, 39B, 39C and 39D by anisotropic etching (for example RIE (Reactive Ion Etching)). An n-type

diffusion region 40 of the selection transistor is formed by ion-implantation using word lines 38A, 38B, 38C and 38D as masks, at the same time all of n-type diffusion regions 32 and 33 are formed (Fig. 3 (a)).

A CVD silicon dioxide layer is then formed on the whole surface, and anisotropically etched to form CVD silicon dioxide side walls of word lines 38A, 38B, 38C and 38D (Fig. 3 (b)).

A CVD silicon dioxide layer is formed on the whole surface, and the portion of the just-formed CVD silicon dioxide layer which is located between word lines 38A and 38B is etched to form CVD silicon dioxide layer 43 having a contact hole 42 to n-type diffusion region 40. A bit line 44 made of a polycide layer is then formed (Fig. 3 (c)).

According to the method as described above, even if contact hole 42 is wide, word lines 38A, 38B, 38C and 38D covered with CVD silicon dioxide layer 43 cannot be etched. Thus, it is unnecessary to consider the superfluous dimension margin L and it is possible to improve the the microminiaturization of the elements. However, the memory cell formed by the method as described above exhibits a large difference in level across the surface thereof. Breakage of bit line 44 on the corner of structure is thus apt to occur often.

To solve the problem described above, a method as shown in Fig. 4 is considered. In this method, before bit line 44 is formed, a silicate glass layer having a low melting point, for example BPSG (Boron Phosphorus Silicate Glass) layer 45, is formed on the whole surface and is flattened by thermal annealing. A contact hole is then formed through this layer. In this structure, a thickness T1 of BPSG layer 45 above word lines 38A and 38B differs from that or a thickness T2 of BPSG layer 45 above n-type diffusion region 40. Thus, when BPSG layer 45 is etched to form a contact hole for a bit line, there is the possibility that word lines 38A and 38B will be exposed, and a connection between one of the word lines and the bit line may be formed.

In the method as described above, it is possible to improve the microminiaturization of the elements, but opening of upper wiring is apt to occur often.

An object of the present invention is to provide a method of manufacturing a semiconductor device suitable for microminiaturizing a contact portion of device elements, the method providing a reliable wiring layer on the corner of structure having different surface levels in which the wiring layer is less susceptible to opening.

According to the present invention, a method of manufacturing a semiconductor device having a semiconductor substrate and conductive members insulatingly formed on said semiconductor sub-

strate, comprises the steps of forming a member insulating layer on the conductive members and on said substrate, forming a contact hole by etching a predetermined part of the member insulating layer between said conductive members, thereby exposing said substrate, forming a first conductive layer on the remaining member insulating layer and in the contact hole, forming a flattening layer on the remaining member insulating layer and the first conductive layer, the surface of said flattening layer having a reduced variation in surface level, exposing a part of the first conductive layer by etching the flattening layer so that the flattening layer remains within said contact hole, and forming a second conductive layer on the remaining flattening layer and the exposed part of the first conductive layer, thereby connecting said second conductive layer to said substrate.

European Patent Application EP-A-0 249 780 describes a semiconductor device in which contact regions are formed in a substrate to be connected to a wiring layer. However, this document does not disclose the subject-matter of Claim 1.

The accompanying drawings, which are incorporated in and constitute a part of this specification, illustrate embodiments of this invention, and, together with the description, serve to explain the principles of the invention.

Fig. 1 is a sectional view showing a conventional semiconductor device for explanation of a method of manufacturing;

Fig. 2 is an equivalent circuit of semiconductor device shown in Fig. 1;

Fig. 3(a), 3(b), and 3(c) are sectional views showing steps of a conventional method of manufacturing a semiconductor device;

Fig. 4 is a sectional view showing a conventional semiconductor device for explanation of method of manufacturing;

Figs. 5(a) to (h) are sectional views showing steps of a method of manufacturing a semiconductor device according to a first embodiment of the present invention;

Fig. 6 is a sectional view showing a semiconductor device for explanation of a method of manufacturing according to a second embodiment of the present invention;

Fig. 7 is a sectional view showing a semiconductor device for explanation of a method of manufacturing according to a third embodiment of the present invention;

Figs. 8(a) and (b) are schematic top views of wiring of a semiconductor device of the present invention according, respectively, to a conventional method and to the method of the present invention.

Referring now to the drawings, a production DRAM (Dynamic Random Access Memory), which

constitutes a preferred embodiment of the invention, will be described in detail.

A first embodiment of the present invention will be described with reference to Figs. 5(a) to (h), which show the steps of manufacturing a DRAM according to the present invention.

A field oxide layer 52 for isolation of elements is formed on the surface of p-type silicon semiconductor substrate 51. A silicon dioxide layer 53 is formed on the surface of semiconductor substrate 51 by thermal oxidation, and a photoresist 54 for use as a mask for ion implementation is formed on silicon dioxide layer 53. N-type impurity regions 55 and 56 are formed by implanting n-type ions, for example As (arsenic), into semiconductor substrate 51 using photoresist 54 (Fig. 5(a)).

Next, photoresist 54 is removed, a polysilicon layer 57 is formed on semiconductor substrate 51 by the CVD (Chemical Vapor Deposition) method, and capacitor electrodes 58 and 59 are formed by patterning polysilicon layer 57 and silicon dioxide layer 53 (Fig. 5(b)).

Next, silicon dioxide layer 60 is formed by oxidizing the surface of capacitor electrodes 58 and 59 and each polysilicon layer 57 by thermal oxidation. A portion of the silicon dioxide layer (not shown) formed on the surface of semiconductor substrate is then removed, so that a corresponding portion 51' of the surface of semiconductor substrate 51 is exposed (Fig. 5(c)).

Next, silicon dioxide layer 61 is formed on the exposed surface 51' of semiconductor substrate 51 by thermal oxidation. This silicon oxide layer 61 will serve as a gate oxide layer of a MOS transistor which shall be formed later and has a thickness of a few ten nm (a few hundred Å) (Fig. 5(d)).

Next, conductive members functioning as word lines are formed, and a member insulating layer is formed on the word lines. It is preferred that the member insulating layer comprises first and second member insulating layers. It is further preferred that the first member insulating layer comprises first and second insulating sublayers. In the preferred embodiment, the conductive members and first member insulating layer are formed by depositing polysilicon and silicon dioxide layers on the whole surface by the CVD method, and by photoetching these layers to form polysilicon word lines 62A, 62B, 62C and 62D and a silicon dioxide first insulating sublayer 63. N-type diffusion region 64 of a selection transistor is then formed by implanting n-type ions, for example As, using word lines 62A, 62B, 62C and 62D and polysilicon layer 57 as masks. N-type impurity regions 65 and 66, which unite with n-type impurity regions 55 and 56 respectively, are thus formed. As a result, n-type impurity regions 55 and 65 and n-type impurity regions 56 and 66 together comprise n-type diffu-

sion regions 67 and 68, so as to form two capacitors. A silicon dioxide layer is formed on the whole surface by the CVD method, and is removed by anisotropic etching (for example, Reactive Ion Etching) to form a silicon dioxide second insulating sublayer 69 remaining on each side wall of each word line 62A, 62B, 62C and 62D (Fig. 5 (e)).

Next, a silicon dioxide layer is formed on the whole surface by the CVD method, and anisotropically etched using a mask to form a second member insulating layer 70. In this case, it is preferable that a thickness of second member insulating layer 70 on sublayer 63 be equal to a thickness of the silicon dioxide layer on n-type diffusion region 64 etched by the RIE method. As a result, contact hole 71 is formed between word lines 62A and 62B (Fig. 5(f)).

Next, a first conductive layer 72 is formed on the member insulating layer (including sublayers 63 and 69 and second member insulating layer 70) and in contact hole 71. Preferably, first conductive layer 72 is constructed in a self-aligned manner by forming a polysilicon layer having a thickness of about 100 nm (1000 Å) on the whole surface by the CVD method at a pressure below atmospheric level, and by selectively removing the polysilicon layer thus formed such that first conductive layer 72 remains so as to cover contact hole 71.

A flattening layer 73 having a thickness of 700 nm (7000 Å) is then formed of a glass having a low melting point, for example, BPSG. BPSG flattening layer 73 is flattened by thermal annealing so as to form a surface having a reduced variation in surface level. A part of first conductive layer 72 is exposed by etching (for example, by wet etching or RIE) BPSG flattening layer 73. As a result, BPSG flattening layer 73 remains in first conductive layer 72 (Fig. 5(g)).

A second conductive layer is then formed on flattening layer 73 and on the exposed part of first conductive layer 72. In the preferred embodiment, the second conductive layer constitutes a bit line 74 constructed by forming a polysilicon layer and a refractory metal layer (for example, molybdenum, tungsten, titanium) in order, and by etching by RIE. Bit line 74 is thus formed of silicide and polysilicon, and is connected with first conductive layer 72 (Fig. 5(h)).

According to the method of manufacturing a semiconductor device as described above, silicon dioxide layer 70 and BPSG flattening layer 73 are formed on capacitor electrodes 58 and 59. Since the surface of BPSG flattening layer 73 is substantially flattened, bit line 74 formed on BPSG flattening layer 73 also becomes flat and thus exhibits a small variation in surface level. Therefore, it is possible to prevent bit corners of line 74 from breaking or opening.

Since first conductive layer 72, which is formed to cover contact hole 71 and to contact bit line 74, is a self-aligned contact structure, it is possible to improve the microminiaturization of the elements.

Moreover, it is possible to establish positive contact between semiconductor substrate 51 and the second conductive layer which forms bit line 74 using polysilicon as the material of first conductive layer 72. Polysilicon has good step coverage, that is, it flows easily and maintains continuity over step structures such as from layers 70 to 63 to 64, without cleaving and forming discontinuities.

It is also possible to lower the resistance value of the wiring by using aluminum as the material of the second conductive layer which forms bit line 74.

A second embodiment of the present invention will be described with reference to Fig. 6, which shows a sectional view of a DRAM for explaining a method of manufacturing.

In the first embodiment of the present invention, after first conductive layer 72 is formed, BPSG flattening layer 73 is formed and is flattened by thermal annealing, and a part of first conductive layer 72 is exposed by etching of the surface of the BPSG layer. As compared with the first embodiment of the present invention, in the second embodiment of the present invention, after a BPSG flattening layer 73A is formed and is flattened, a contact hole 71A is formed in a BPSG layer by using masks, and bit line 74 is formed on the surface of structure.

A third embodiment of the present invention will now be described with reference to Fig. 7, which shows a sectional view of a DRAM for explaining the method of manufacturing.

The steps of the method of this embodiment are the same as shown in Figs. 5(a) to (f). A polysilicon first conductive layer 72A is formed on the whole surface. After a flattening layer 73B of silicate glass having a low melting point (for example, BPSG) and having a thickness of 700 nm (7000 Å) is formed on the whole surface, BPSG flattening layer 73B is flattened by annealing. BPSG flattening layer 73B remains in hollows of first conductive layer 72A only and, except for the hollows, first conductive layer 72A is exposed by etching the surface of the BPSG layer. An aluminum second conductive layer 74B is formed on the whole surface. A bit line is formed by patterning of first conductive layer 72A, BPSG flattening layer 73B, and second conductive layer 74B.

According to the method of manufacturing a semiconductor device as described above, since BPSG flattening layer 73B remains in the hollows in addition to the contact hole, overall flatness of the surface situated below second conductive layer 74B is improved. As a result, it is possible to

prevent second conductive layer 74B from opening.

Moreover, since the bit line consists essentially of polysilicon first conductive layer 72A and aluminum second conductive layer 74B, even if either layer 72A or layer 74B is opened, the bit line is not opened electrically. It is thus possible to improve reliability of a semiconductor device according to the present invention.

Fig. 8(a) shows a pattern of wiring on a contact hole having a wiring fringe according to prior art. Fig. 8(b) shows a pattern of wiring on a contact hole not having wiring fringe according to the present invention.

Pattern gaps sometimes occur in the mask used to form the wiring layer of a semiconductor device. This can result in an increase in resistance of the wiring layer. To avoid such a resistance increase, semiconductor devices formed according to methods of the prior art often included a wiring fringe 91, as shown in Fig. 8(a). However, this limited the degree of microminiaturization which could be achieved. In semiconductor devices manufactured according to the present invention, the surface of the layer below the bit line on the contact hole is flattened. Thus, even if a pattern gap of the wiring layer mask is present, an increase of wiring layer resistance will not occur. Therefore, as shown in Fig. 8(b), the wiring pattern can be made straight without a wiring fringe, thus improving the microminiaturization of wiring.

The present invention is not limited to the embodiment as described above, but modifications can be made.

For example, the material of the first conductive layer may be of the silicon material group (for example, crystal silicon, amorphous silicon) instead of polysilicon.

Moreover, the material of the flattening layer may be PSG (Phosphorus Silicate Glass) or BSG (Born Silicate Glass) instead of BPSG. Moreover, the material of the flattening layer may be SOG (Spin On Glass) which is liquid from the beginning of the process, instead of BPSG. In the present method when using SOG, liquid SOG is coated on a semiconductor substrate by spinning, and the SOG is hardened by evaporating the solvent portion of the SOG at a temperature of 100°C - 500°C. As a result, the contact hole or differences in level of surfaces are covered by the SOG layer.

Moreover, the material of the first conductive layer may be aluminum instead of polysilicon. However, in the present method when using aluminum as a material of the first conductive layer, SOG (Spin On Glass) must be used as the material of the flattening layer instead of BPSG, since it is impossible to flatten the layer by annealing.

Moreover, it is possible to reduce the value of

the resistance of the word line by performing ion implantation on the polysilicon layer.

Moreover, the material of bit line may be a refractory metal silicide (for example, MoSi₂, TiSi₂, WSi) or a refractory metal (for example, Mo, Ti, W) or a polycide, instead of silicide.

According to the methods and apparatus of the invention as described above, reliability of a semiconductor device can be improved, and a highly integrated semiconductor device can be realized.

Claims

1. A method of manufacturing a semiconductor device having a semiconductor substrate (51) and conductive members (62A; 62B) insulatingly formed on said semiconductor substrate (51), the method comprising the steps of:
 - forming a member insulating layer (63, 69, 70) on the conductive members (62A; 62B) and on said substrate (51);
 - forming a contact hole (71) by etching a predetermined part of the member insulating layer (63, 69, 70) between said conductive members (62A; 62B), thereby exposing said substrate (51);
 - forming a first conductive layer (72) on the remaining member insulating layer (63, 69, 70) and in the contact hole (71);
 - forming a flattening layer (73) on the remaining member insulating layer (63, 69, 70) and the first conductive layer (72), the surface of said flattening layer (73) having a reduced variation in surface level;
 - exposing a part of the first conductive layer (72) by etching the flattening layer (73) so that the flattening layer remains within said contact hole (71); and
 - forming a second conductive layer (74) on the remaining flattening layer (73) and the exposed part of the first conductive layer (72), thereby connecting said second conductive layer (74) to said substrate (51).
2. A method as recited in claim 1, wherein the step of forming the member insulating layer (63, 69, 70) comprises the steps of forming first and second member insulating layers (63, 69; 70).
3. A method as recited in claim 2, wherein the step of forming the member-insulating layer (63, 69; 70) comprises the step of forming the first member insulating layer (63, 69) over the conductive members (62A; 62B) in a self-aligned manner.
4. A method as recited in claim 2, wherein the

prevent second conductive layer 74B from opening.

Moreover, since the bit line consists essentially of polysilicon first conductive layer 72A and aluminum second conductive layer 74B, even if either layer 72A or layer 74B is opened, the bit line is not opened electrically. It is thus possible to improve reliability of a semiconductor device according to the present invention.

Fig. 8(a) shows a pattern of wiring on a contact hole having a wiring fringe according to prior art. Fig. 8(b) shows a pattern of wiring on a contact hole not having wiring fringe according to the present invention.

Pattern gaps sometimes occur in the mask used to form the wiring layer of a semiconductor device. This can result in an increase in resistance of the wiring layer. To avoid such a resistance increase, semiconductor devices formed according to methods of the prior art often included a wiring fringe 91, as shown in Fig. 8(a). However, this limited the degree of microminiaturization which could be achieved. In semiconductor devices manufactured according to the present invention, the surface of the layer below the bit line on the contact hole is flattened. Thus, even if a pattern gap of the wiring layer mask is present, an increase of wiring layer resistance will not occur. Therefore, as shown in Fig. 8(b), the wiring pattern can be made straight without a wiring fringe, thus improving the microminiaturization of wiring.

The present invention is not limited to the embodiment as described above, but modifications can be made.

For example, the material of the first conductive layer may be of the silicon material group (for example, crystal silicon, amorphous silicon) instead of polysilicon.

Moreover, the material of the flattening layer may be PSG (Phosphorus Silicate Glass) or BSG (Boron Silicate Glass) instead of BPSG. Moreover, the material of the flattening layer may be SOG (Spin On Glass) which is liquid from the beginning of the process, instead of BPSG. In the present method when using SOG, liquid SOG is coated on a semiconductor substrate by spinning, and the SOG is hardened by evaporating the solvent portion of the SOG at a temperature of 100°C - 500°C. As a result, the contact hole or differences in level of surfaces are covered by the SOG layer.

Moreover, the material of the first conductive layer may be aluminum instead of polysilicon. However, in the present method when using aluminum as a material of the first conductive layer, SOG (Spin On Glass) must be used as the material of the flattening layer instead of BPSG, since it is impossible to flatten the layer by annealing.

Moreover, it is possible to reduce the value of

the resistance of the word line by performing ion implantation on the polysilicon layer.

Moreover, the material of bit line may be a refractory metal silicide (for example, MoSi₂, TiSi₂, WSi) or a refractory metal (for example, Mo, Ti, W) or a polycide, instead of silicide.

According to the methods and apparatus of the invention as described above, reliability of a semiconductor device can be improved, and a highly integrated semiconductor device can be realized.

Claims

1. A method of manufacturing a semiconductor device having a semiconductor substrate (51) and conductive members (62A; 62B) insulatingly formed on said semiconductor substrate (51), the method comprising the steps of:
 - forming a member insulating layer (63, 69, 70) on the conductive members (62A; 62B) and on said substrate (51);
 - forming a contact hole (71) by etching a predetermined part of the member insulating layer (63, 69, 70) between said conductive members (62A; 62B), thereby exposing said substrate (51);
 - forming a first conductive layer (72) on the remaining member insulating layer (63, 69, 70) and in the contact hole (71);
 - forming a flattening layer (73) on the remaining member insulating layer (63, 69, 70) and the first conductive layer (72), the surface of said flattening layer (73) having a reduced variation in surface level;
 - exposing a part of the first conductive layer (72) by etching the flattening layer (73) so that the flattening layer remains within said contact hole (71); and
 - forming a second conductive layer (74) on the remaining flattening layer (73) and the exposed part of the first conductive layer (72), thereby connecting said second conductive layer (74) to said substrate (51).
2. A method as recited in claim 1, wherein the step of forming the member insulating layer (63, 69, 70) comprises the steps of forming first and second member insulating layers (63, 69; 70).
3. A method as recited in claim 2, wherein the step of forming the member insulating layer (63, 69; 70) comprises the step of forming the first member insulating layer (63, 69) over the conductive members (62A; 62B) in a self-aligned manner.
4. A method as recited in claim 2, wherein the



step of forming the first member insulating layer (63, 69) comprises the substeps of forming first and second insulating sublayers (63, 69).

5. A method as recited in claim 4, wherein the step of forming a first conductive layer (72) comprises the step of forming the first conductive layer (72) by depositing a vapor of conductive material at a pressure below atmospheric level.
6. A method as recited in claim 4, wherein the first conductive layer (72) comprises polysilicon.
7. A method as recited in claim 1, wherein the second conductive layer (74) comprises a material containing a metal.
8. A method as recited in claim 7, wherein the second conductive layer (74) comprises aluminum.
9. A method as recited in claim 1, wherein the flattening layer (73) comprises a silicate glass including a material selected from the group consisting of boron and phosphorus.
10. A method as recited in claim 9, wherein the silicate glass (73) consists essentially of a material selected from the group consisting of BPSG, PSG, and BSG.
11. A method as recited in claim 1, wherein the step of forming the flattening layer (73) comprises the step of forming the flattening layer (73) of a silicate glass by spin coating.
12. A method as recited in claim 1, wherein the conductive members (62A; 62B) form word lines.

Patentansprüche

1. Verfahren zum Herstellen einer Halbleiter-Vorrichtung, die ein Halbleitersubstrat (51) und leitende Gebiete (62A; 62B) aufweist, die auf dem isolierten Halbleitersubstrat (51) gebildet sind, wobei bei diesem Verfahren:
 - eine isolierende Schicht (63, 69, 70) auf den leitenden Gebieten (62A; 62B) und dem Substrat (51) gebildet wird;
 - ein Kontaktloch (71) gebildet wird, wozu ein bestimmter Teil der isolierenden Schicht (63, 69, 70) zwischen den leitenden Gebieten (62A; 62B) weggeätzt wird, wodurch das Substrat (51) freigelegt

wird;

- eine erste leitende Schicht (72) auf der verbliebenen isolierenden Schicht (63, 69, 70) und in dem Kontaktloch (71) gebildet wird;
- eine Glättungsschicht (73) auf der verbliebenen isolierenden Schicht (63, 69, 70) und der ersten leitenden Schicht (72) gebildet wird, wobei die Oberfläche der Glättungsschicht (73) eine verminderte Oberflächeniveauvariation aufweist;
- ein Teil der ersten leitenden Schicht (72) freigelegt wird, wozu die Glättungsschicht (73) weggeätzt wird in dem Masse daß die Glättungsschicht im Kontaktloch (71) zurückbleibt, und
- eine zweite leitende Schicht (74) auf der verbliebenen Glättungsschicht (73) und dem freigelegten Teil der ersten leitenden Schicht (72) gebildet wird, wodurch die zweite leitende Schicht (74) mit dem Substrat (51) verbunden wird.

2. Verfahren gemäß Anspruch 1, bei dem bei dem Schritt zur Bildung der isolierenden Schicht (63, 69, 70) eine erste und eine zweite isolierende Schicht (63, 69; 70) gebildet wird.
3. Verfahren gemäß Anspruch 2, bei dem bei dem Schritt zur Bildung der isolierenden Schicht (63, 69; 70) die erste isolierende Schicht (63, 69) in einer selbstausgerichteten Weise über den leitenden Gebieten (62A; 62B) gebildet wird.
4. Verfahren gemäß Anspruch 2, bei dem bei dem Schritt zur Bildung der ersten isolierenden Schicht (63, 69) eine erste und zweite isolierende Teilschicht (63, 69) gebildet wird.
5. Verfahren gemäß Anspruch 4, bei dem bei dem Schritt zur Bildung der ersten leitenden Schicht (72) diese erste leitende Schicht (72) durch Aufdampfen eines leitenden Materials bei einem geringeren Druck als Atmosphärendruck gebildet wird.
6. Verfahren gemäß Anspruch 4, bei dem die erste leitende Schicht (72) Polysilizium enthält.
7. Verfahren gemäß Anspruch 1, bei dem die zweite leitende Schicht (74) ein Material enthält, das ein Metall aufweist.
8. Verfahren gemäß Anspruch 7, bei dem die zweite leitende Schicht (74) Aluminium enthält.
9. Verfahren gemäß Anspruch 1, bei dem die



Glättungsschicht (73) ein Silikatglas enthält, das ein Material aufweist, das aus der von Bor und Phosphor gebildeten Gruppe ausgewählt ist.

10. Verfahren gemäß Anspruch 9, bei dem das Silikatglas (73) im wesentlichen aus einem Material besteht, das aus der von BPSG, PSG und BSG gebildeten Gruppe ausgewählt ist.
11. Verfahren gemäß Anspruch 1, bei dem bei dem Schritt zur Bildung der Glättungsschicht (73) diese Glättungsschicht (73) aus einem Silikatglas durch Schleuderbeschichtung gebildet wird.
12. Verfahren gemäß Anspruch 1, bei dem die leitenden Gebiete (62A; 62B) Wortleitungen bilden.

Revendications

1. Un procédé de fabrication d'un dispositif à semiconducteur comprenant un substrat semiconducteur (51) et des éléments conducteurs (62A; 62B) formés et isolés sur ledit substrat semiconducteur (51), le procédé comprenant les étapes suivantes:

formation d'un élément de couche isolante (63, 69, 70) sur les éléments conducteurs (62A; 62B) et sur ledit substrat (51);

formation d'un trou de contact (71) par gravure d'une partie prédéterminée de l'élément de couche isolante (63, 69, 70) entre lesdits éléments conducteurs (62A; 62B), exposant ainsi ledit substrat (51);

formation d'une première couche conductrice (72) sur l'élément de couche isolante restant (63, 69, 70) et dans le trou de contact (71);

formation d'une couche d'aplanissement (73) sur l'élément de couche isolante restant (63, 69, 70) et sur la première couche conductrice (72), la surface de ladite couche d'aplanissement (73) ayant une variation réduite dans le niveau de surface;

exposition d'une partie de la première couche conductrice (72) par gravure de la couche d'aplanissement (73) de sorte que la couche d'aplanissement reste dans ledit trou de contact (71); et

formation d'une deuxième couche conductrice (74) sur la couche d'aplanissement restante (73) et sur la partie exposée de la première couche conductrice (72), pour connecter ainsi ladite deuxième couche conductrice (74) au dit substrat (51).

2. Un procédé selon la revendication 1, dans lequel l'étape de formation de l'élément de couche isolante (63, 69, 70) comprend les étapes de formation d'un premier et d'un deuxième élément de couche isolante (63; 69; 70).

3. Un procédé selon la revendication 2, dans lequel l'étape de formation de l'élément de couche isolante (63; 69; 70) comprend l'étape de formation du premier élément de couche isolante (63, 69) sur les éléments conducteurs (62A; 62B) d'une manière auto-alignée.

4. Un procédé selon la revendication 2, dans lequel l'étape de formation du premier élément de couche isolante (63, 69) comprend les sous-étapes de formation d'une première et d'une deuxième sous-couche isolante (63, 69).

5. Un procédé selon la revendication 4, dans lequel l'étape de formation d'une première couche conductrice (72) comprend l'étape de formation de la première couche conductrice (72) par dépôt en phase vapeur d'un matériau conducteur à une pression en-dessous du niveau atmosphérique.

6. Un procédé selon la revendication 4, dans lequel la première couche conductrice (72) comprend du polysilicium.

7. Un procédé selon la revendication 1, dans lequel la deuxième couche conductrice (74) comprend un matériau contenant un métal.

8. Un procédé selon la revendication 7, dans lequel la deuxième couche conductrice (74) comprend de l'aluminium.

9. Un procédé selon la revendication 1, dans lequel la couche d'aplanissement (73) comprend un verre de silicate englobant un matériau choisi dans le groupe constitué de boron et de phosphore.

10. Un procédé selon la revendication 9, dans lequel le verre de silicate (73) est composé essentiellement d'un matériau choisi dans le groupe constitué de BPSG, PSG et BSG.

11. Un procédé selon la revendication 1, dans lequel l'étape de formation de la couche d'aplanissement (73) comprend l'étape de formation de la couche d'aplanissement (73) en un verre de silicate par revêtement par centrifugation.

12. Un procédé selon la revendication 1, dans



lequel les éléments conducteurs (62A, 62B)
forment des lignes de mot.

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